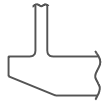


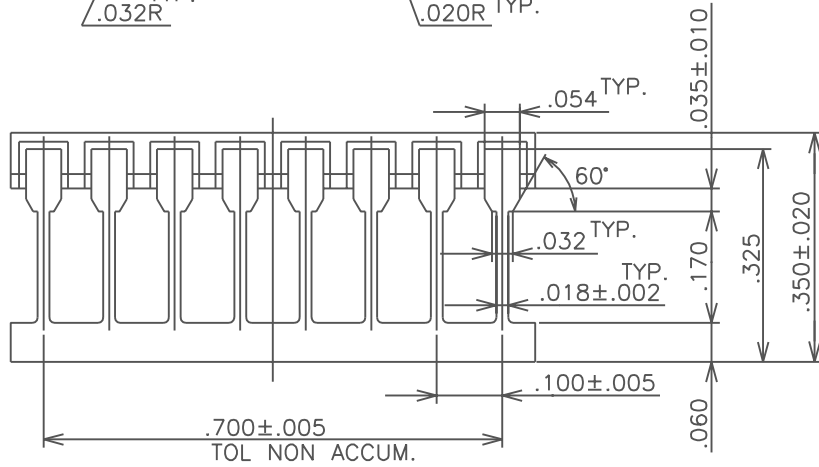
DETAIL-A

NOTES

1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
2. SEAL AREA TO BE METALLIZED.
3. DIE ATTACH AREA TO BE METALLIZED.
4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
5. LEAD RESISTANCE : 0.5 OHM MAX.



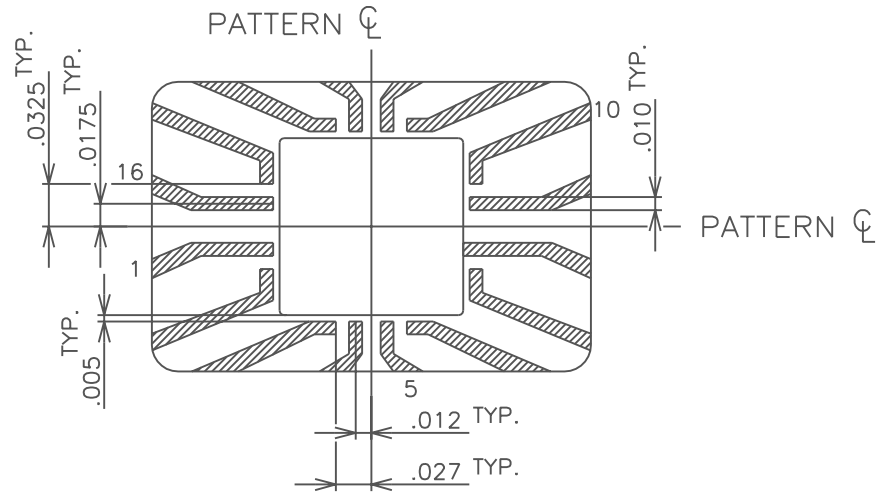
VENDOR'S OPTION



SB016S741-1 S=0 D=0

MODIFICATION					NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
					16 LEAD SIDE BRAZED PACKAGE	UNLESS OTHERWISE SPECIFIED	Y.M	K.O	K.M	AUG.20.'86
					SCALE 5 / 1	MATERIAL				
					AS INDICATED	±.005				
					THIRD ANGLE PROJECTION					
	CHANGED		DATE	DRAWN	CHECKED	APPROVED	DRAWING NO.			SHEET
							KD-S86741			1 / 2
					KYOCERA CORPORATION KYOTO JAPAN					





BONDING PATTERN

MODIFICATION						NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
						16 LEAD SIDE BRAZED PACKAGE	UNLESS OTHERWISE SPECIFIED	Y.M	K.O	K.M	AUG.20.'86
						SCALE 10 / 1	MATERIAL				
							THIRD ANGLE PROJECTION				
	CHANGED	DATE	DRAWN	CHECKED	APPROVED	KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO.	KD-S86741		SHEET	2 / 2